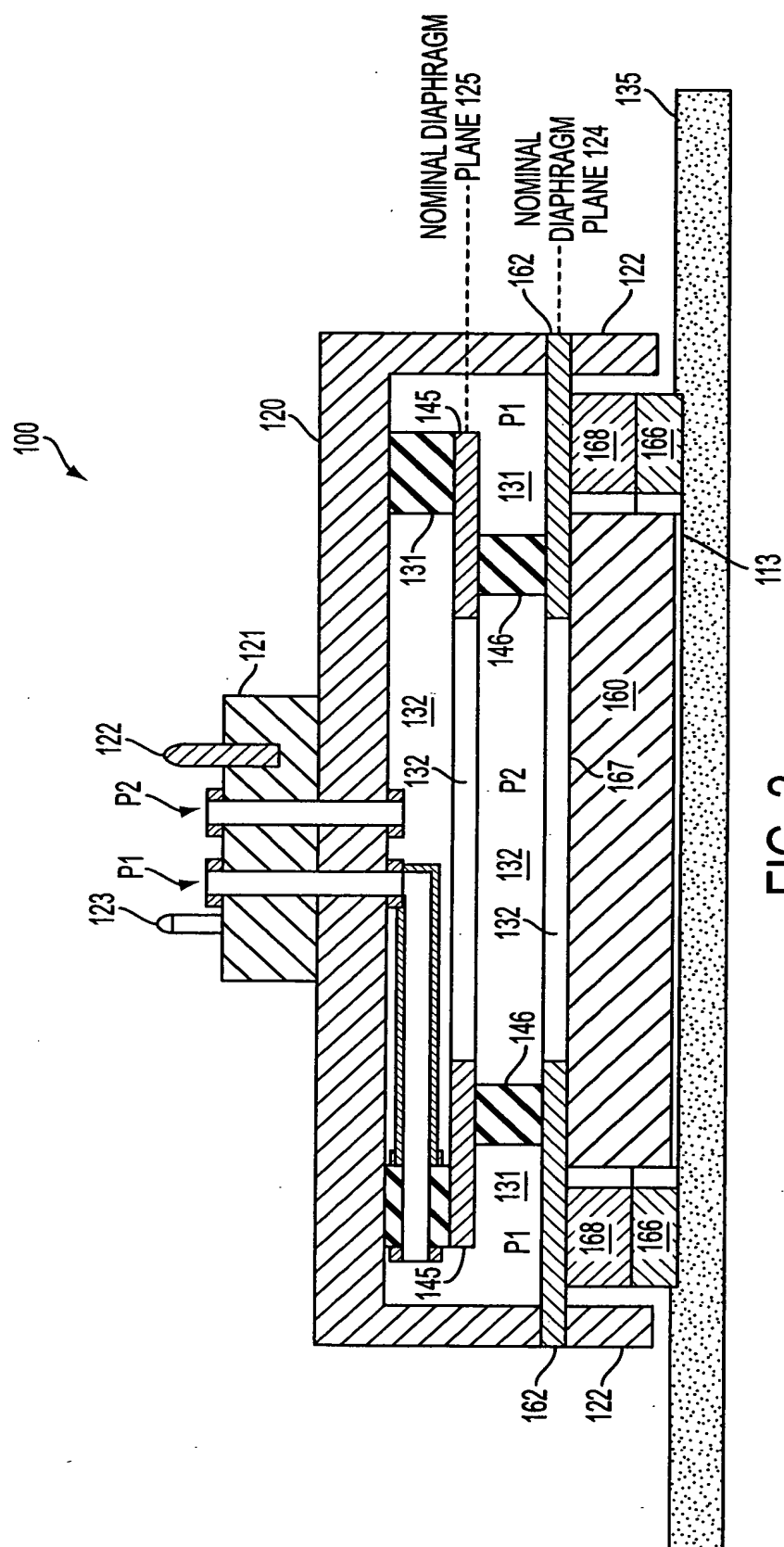


FIG. 1







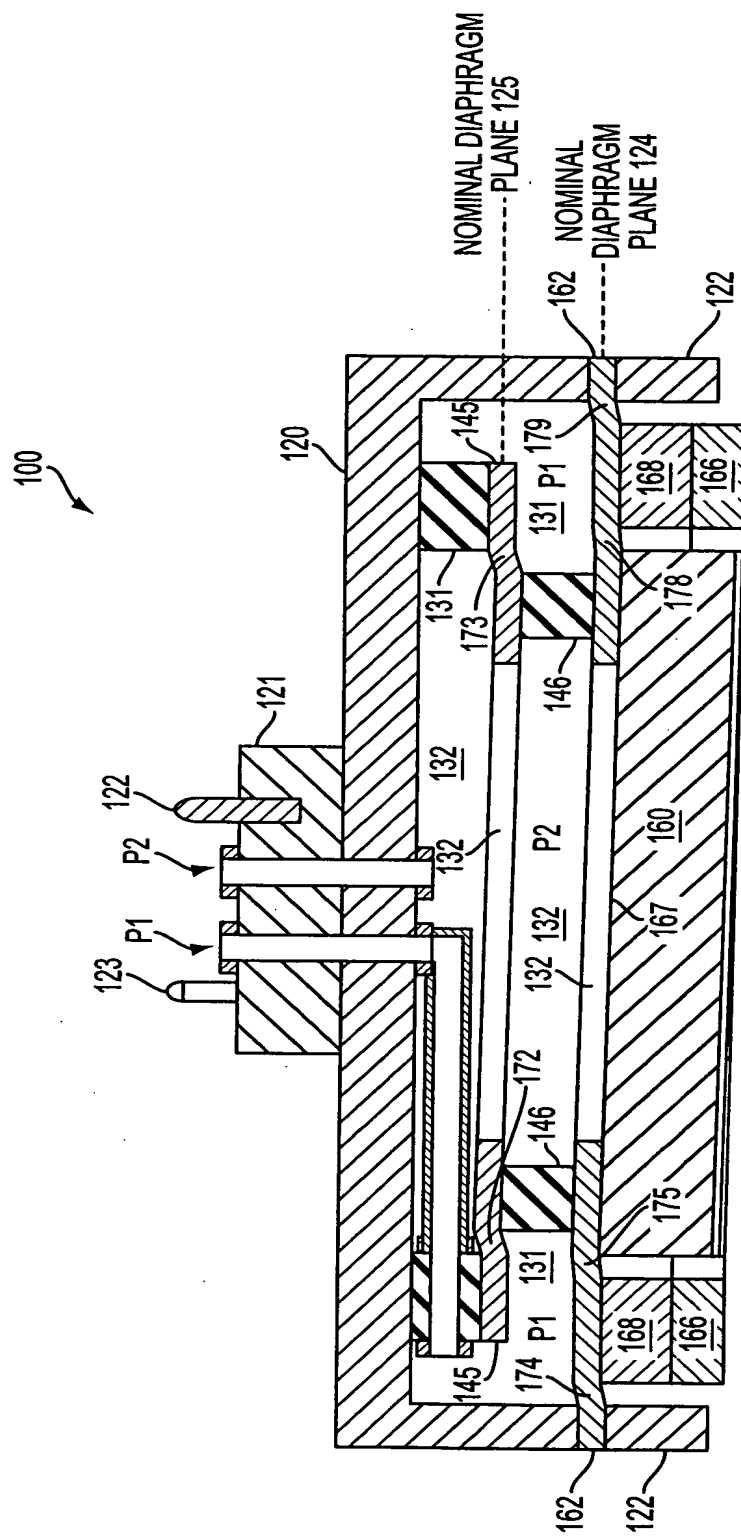


FIG. 3



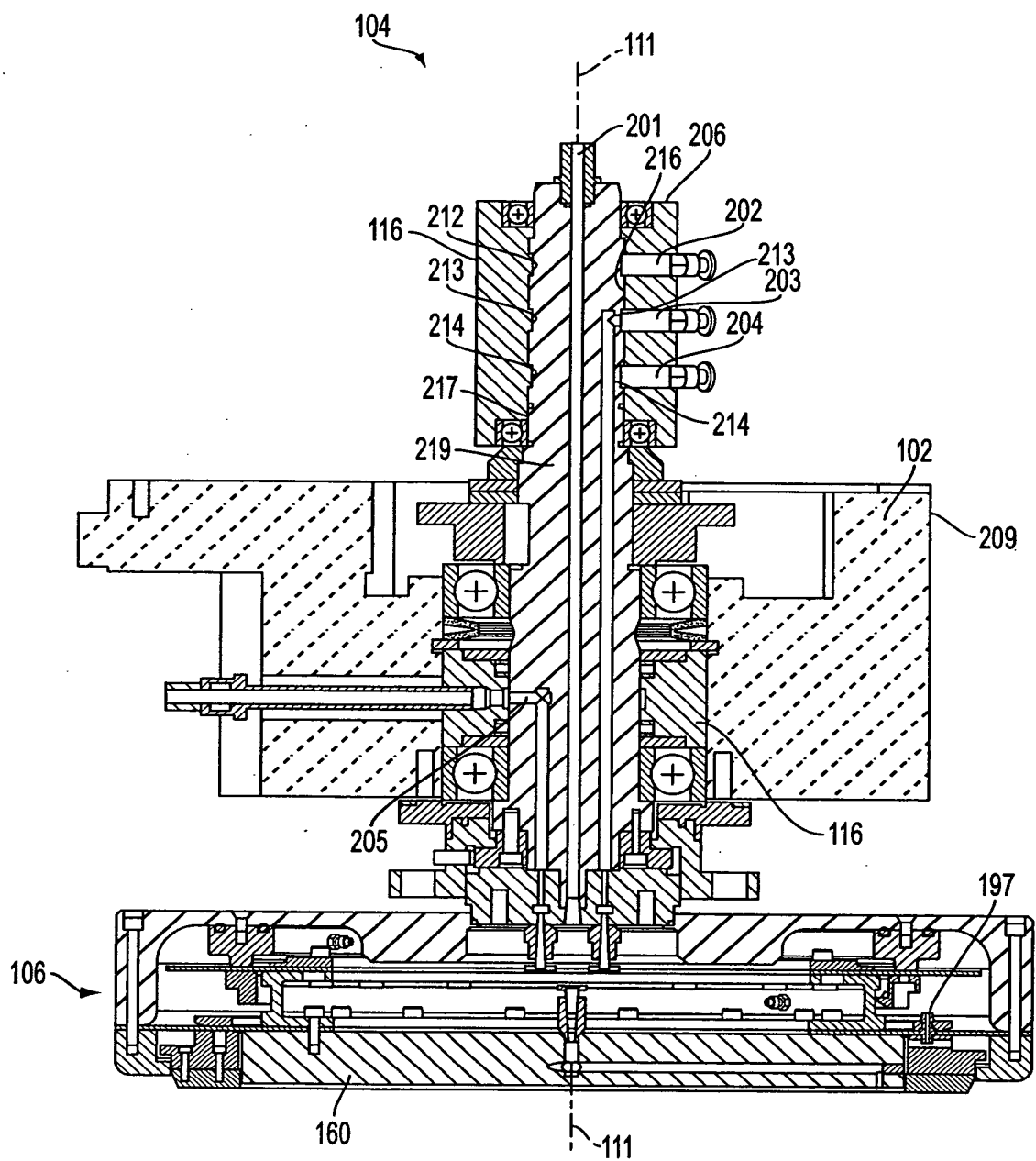


FIG. 4



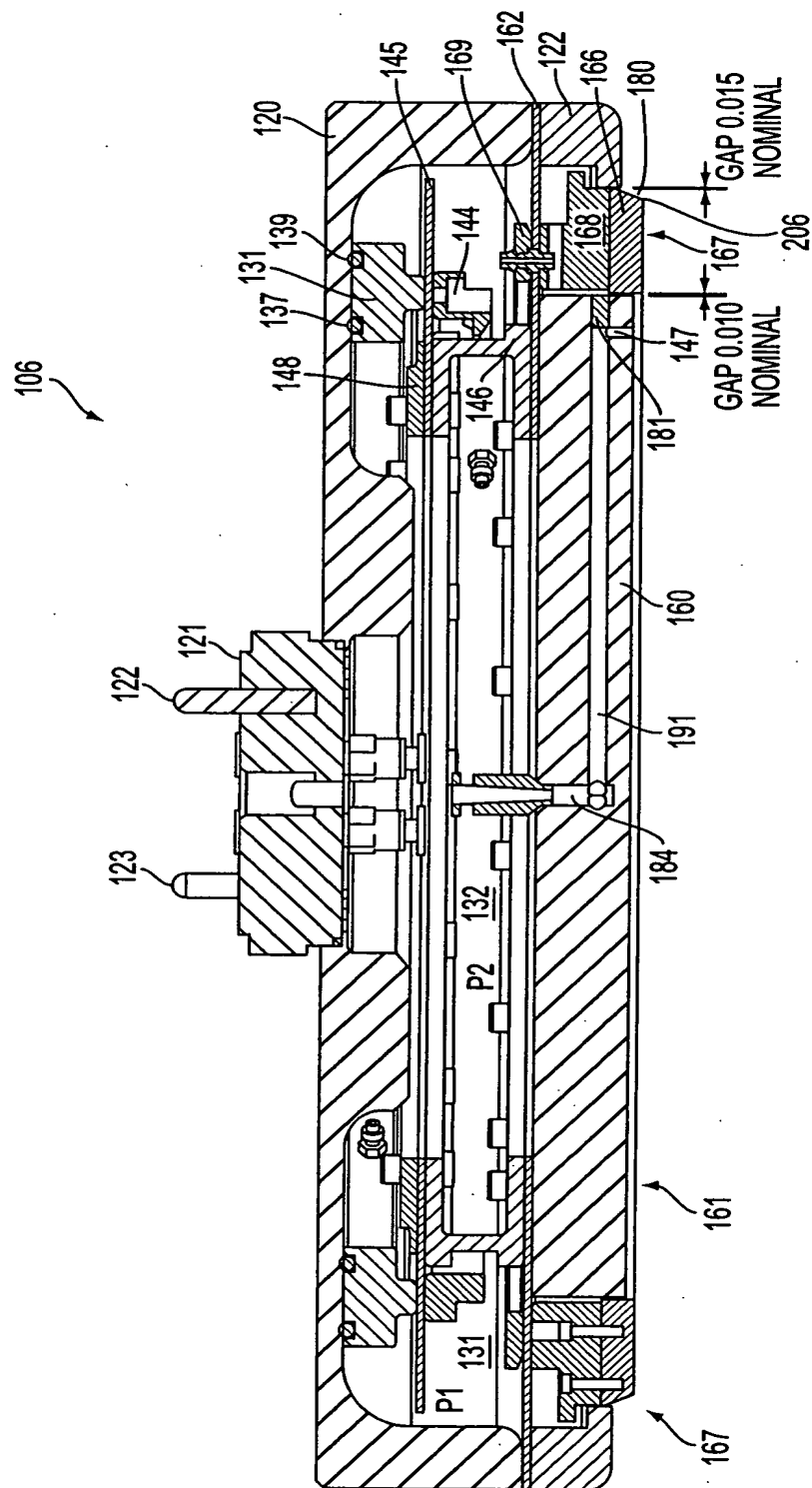


FIG. 5



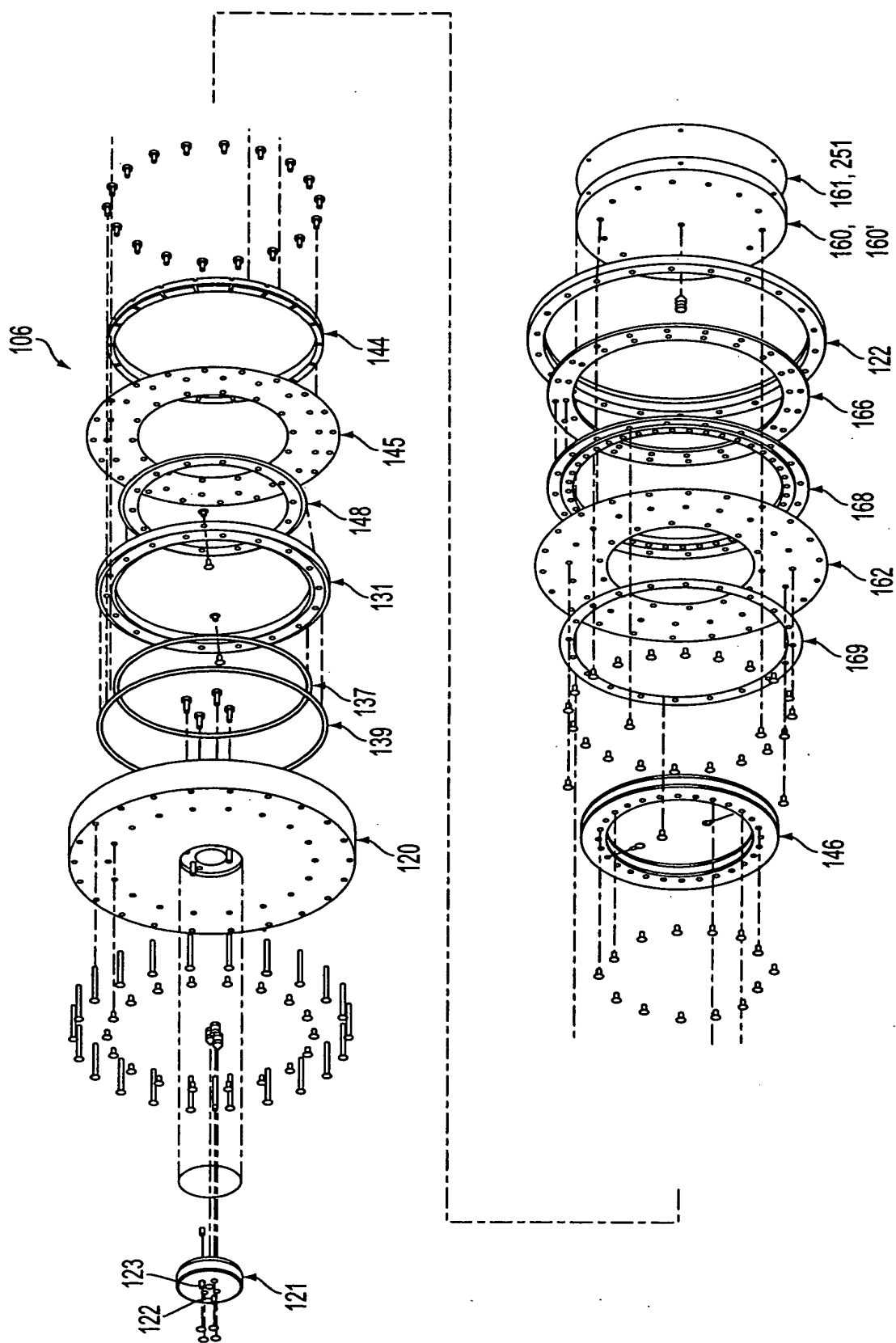


FIG. 6



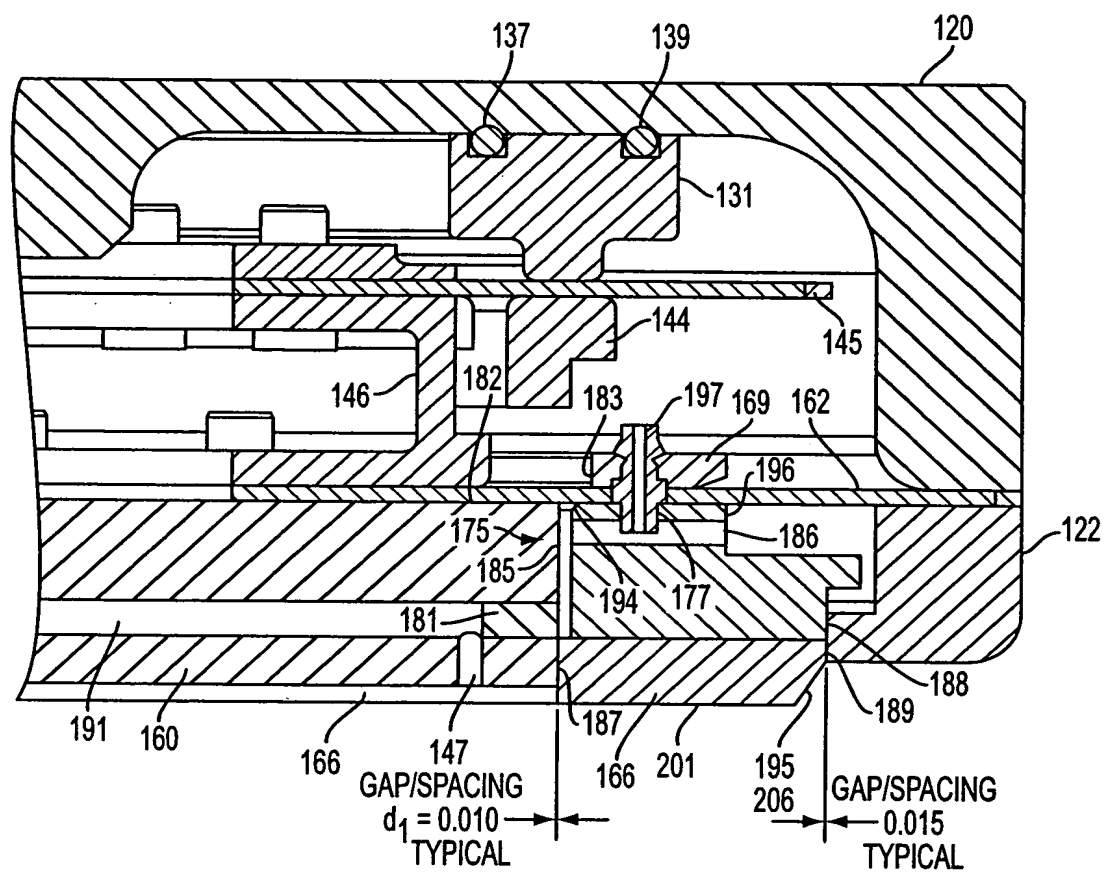


FIG. 7



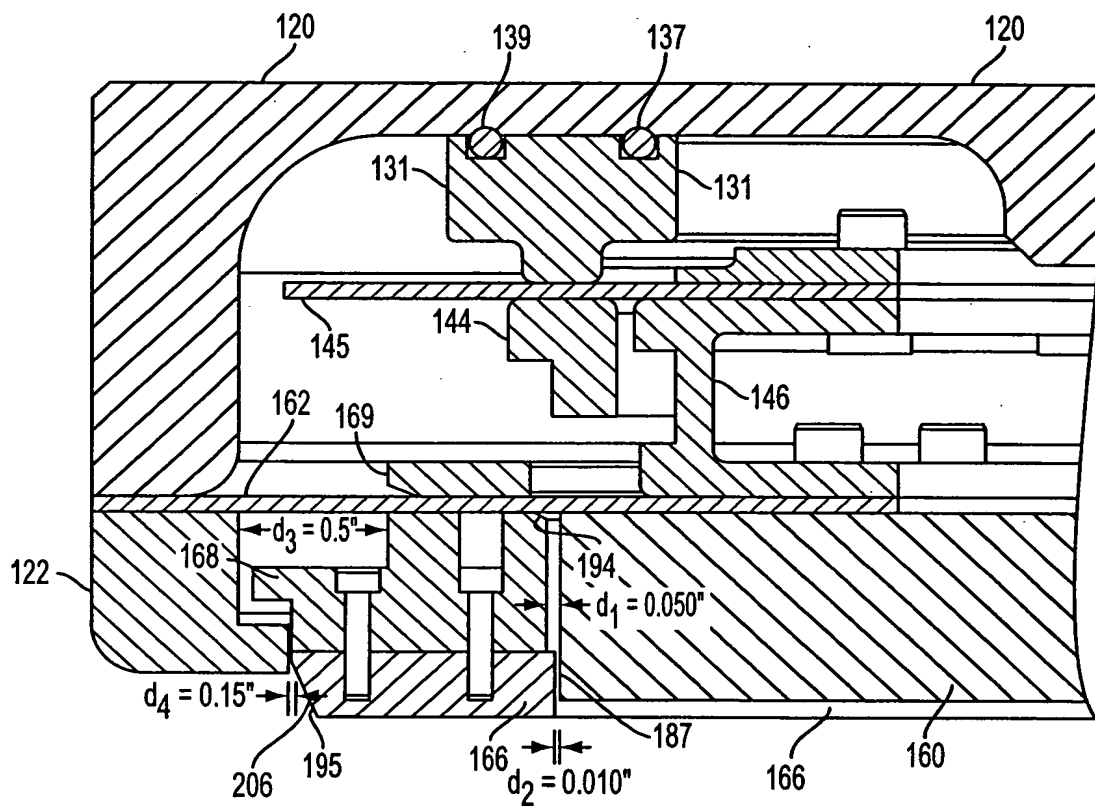


FIG. 8



(20X) 2-56 UNC-28  
(20X) 2-56 UNC-28

166

250±.002 SEE FIG. 13

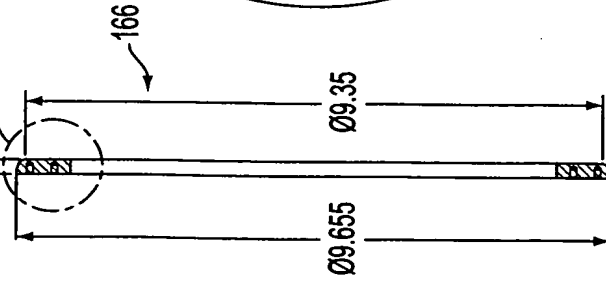


FIG. 10

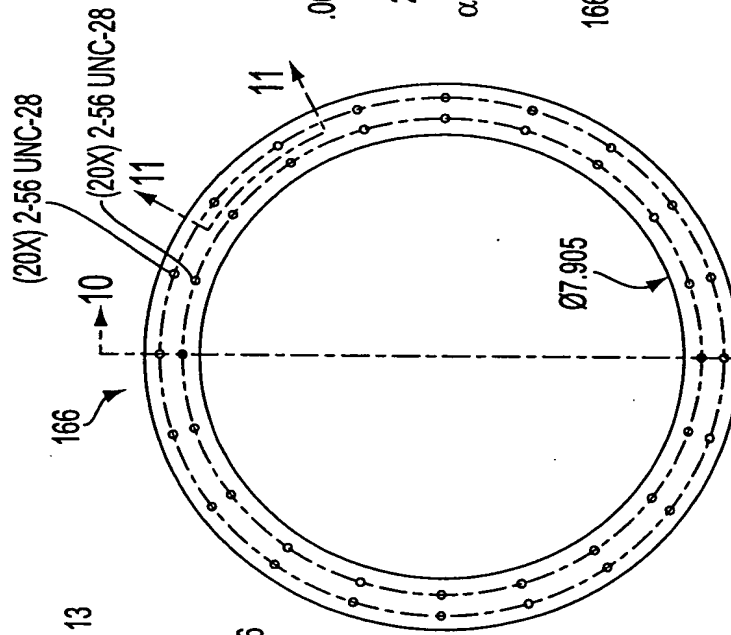


FIG. 9

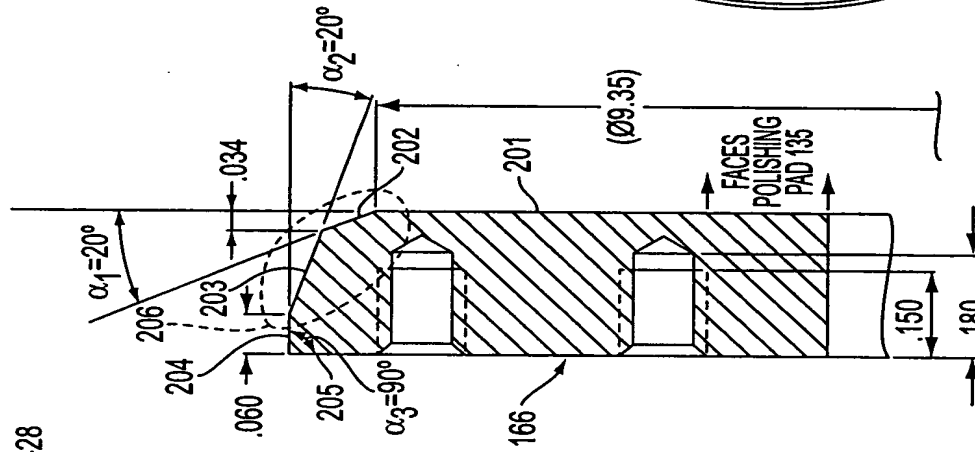


FIG. 13

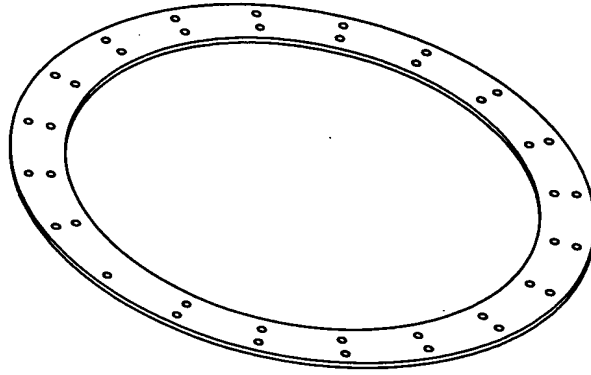


FIG. 12

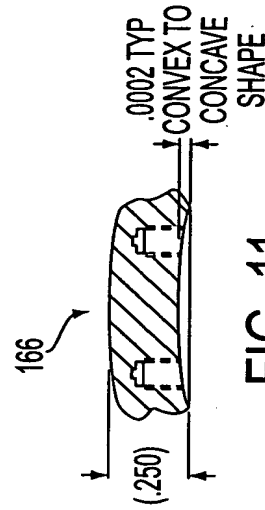


FIG. 11



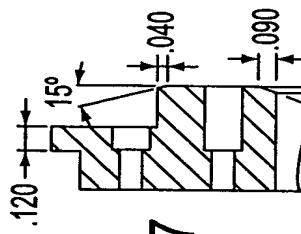


FIG. 17

(20X) Ø.102 THRU  
C'BORE Ø.160 X .30 DEEP  
EQ. SP. ON Ø8.430 B.C.

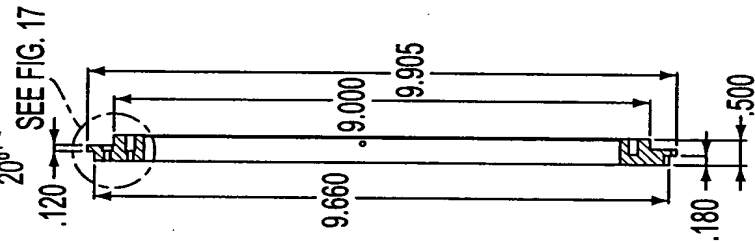


FIG. 15

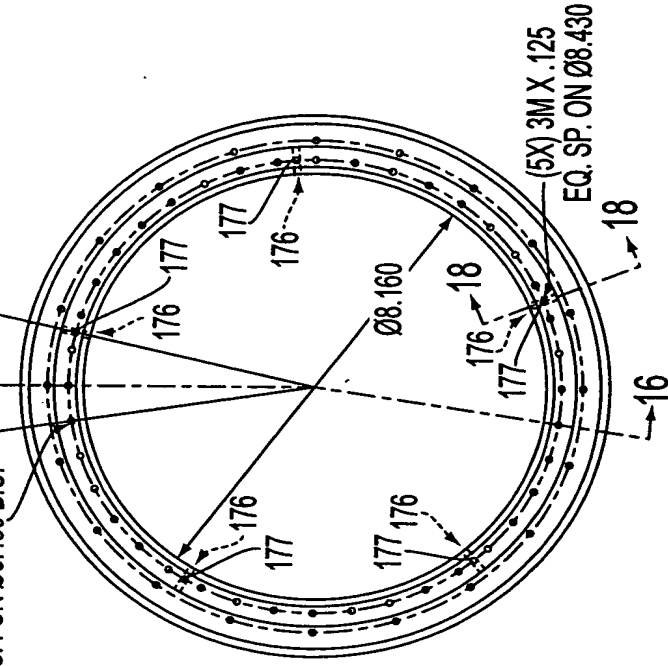


FIG. 14

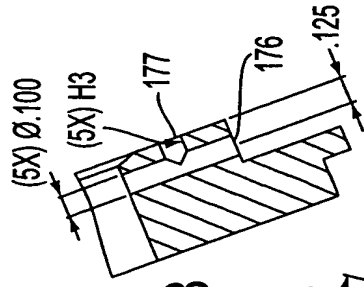


FIG. 18

(20X) 6-32 UNC-28 X T.25  
EQ. SP. ON Ø8.430 B.C.

(5X) Ø.100  
(5X) H3  
177  
176  
125

FIG. 16



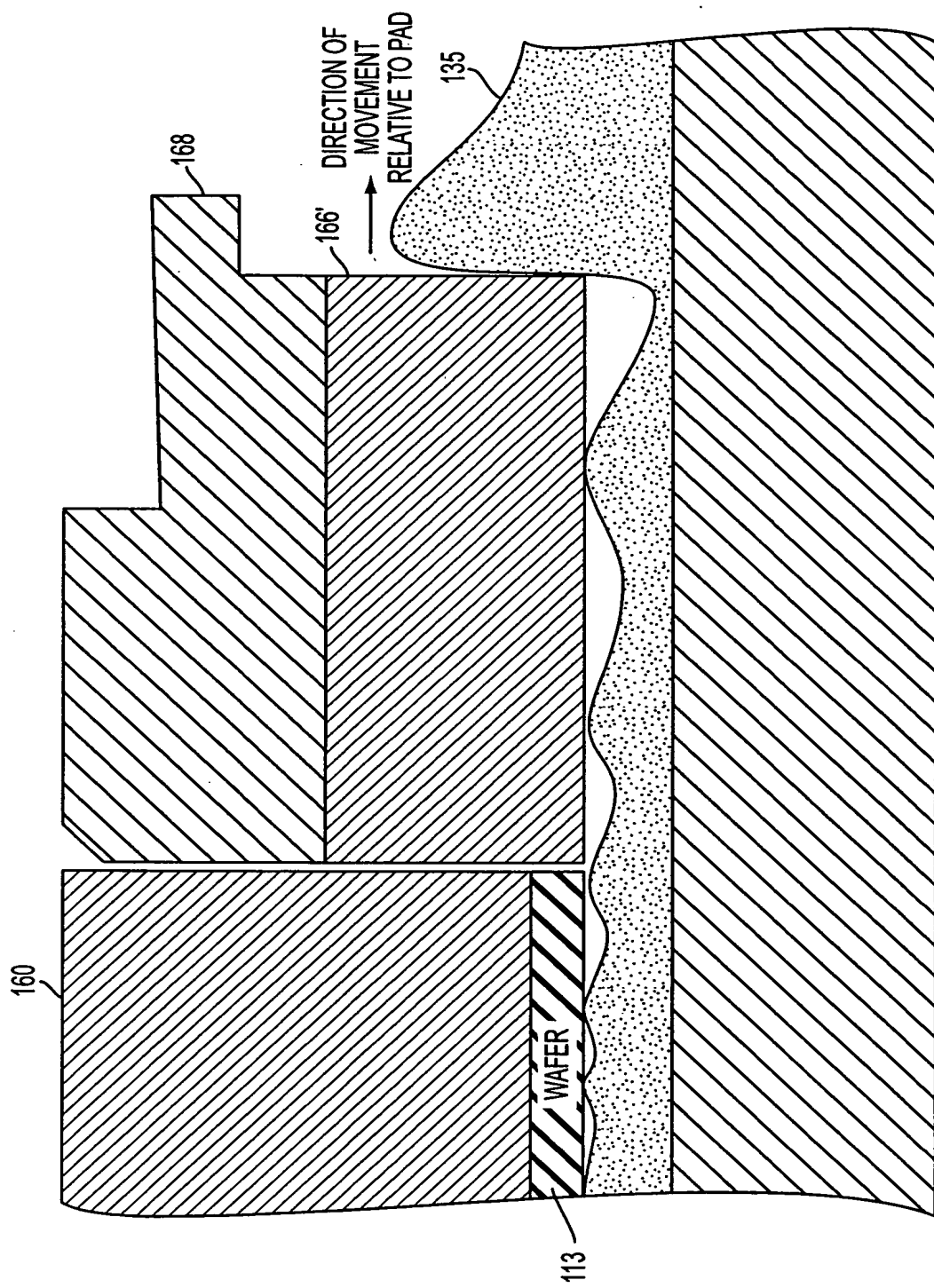


FIG. 19



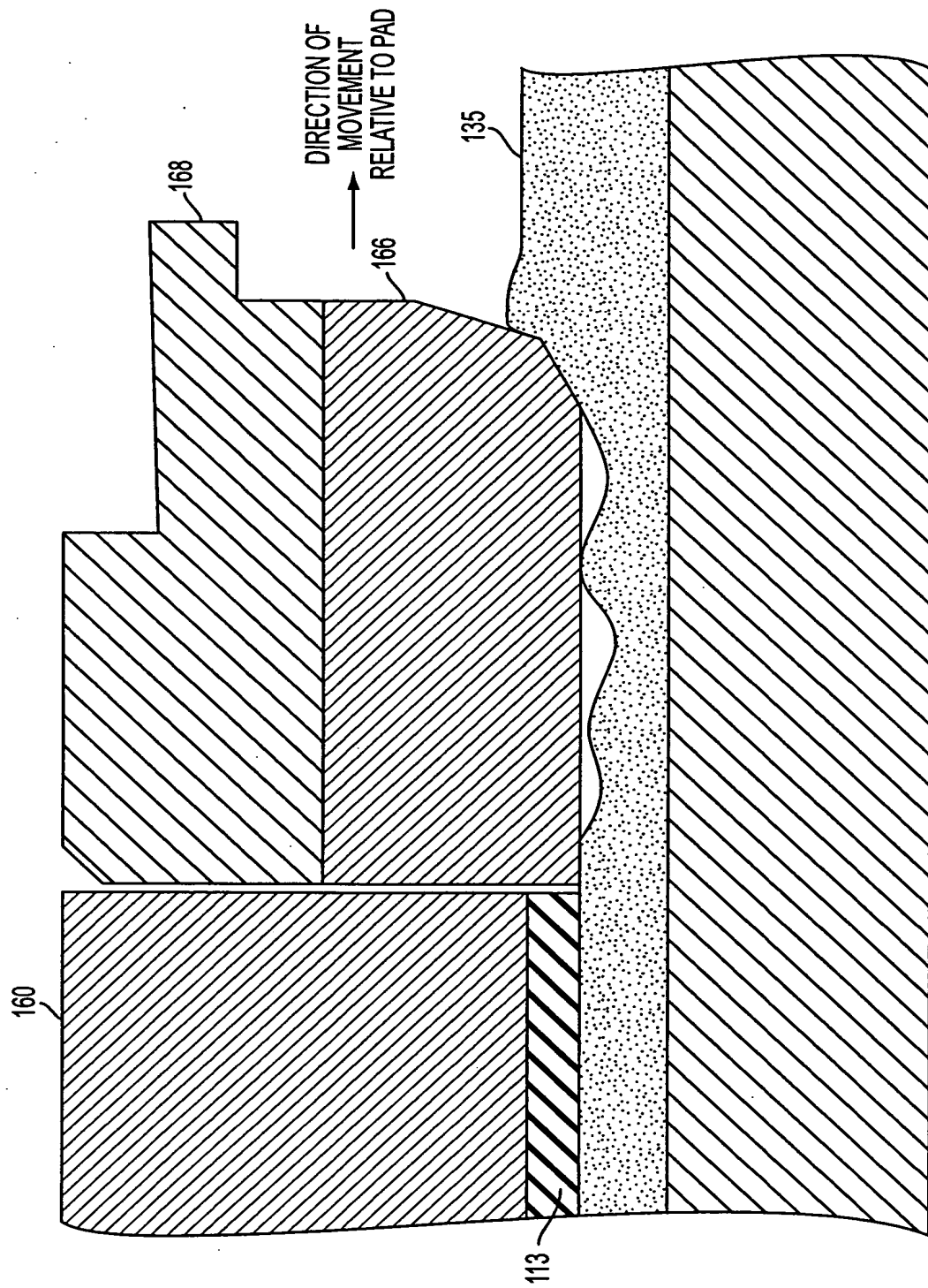


FIG. 20



# WAFER LOADING PROCEDURE

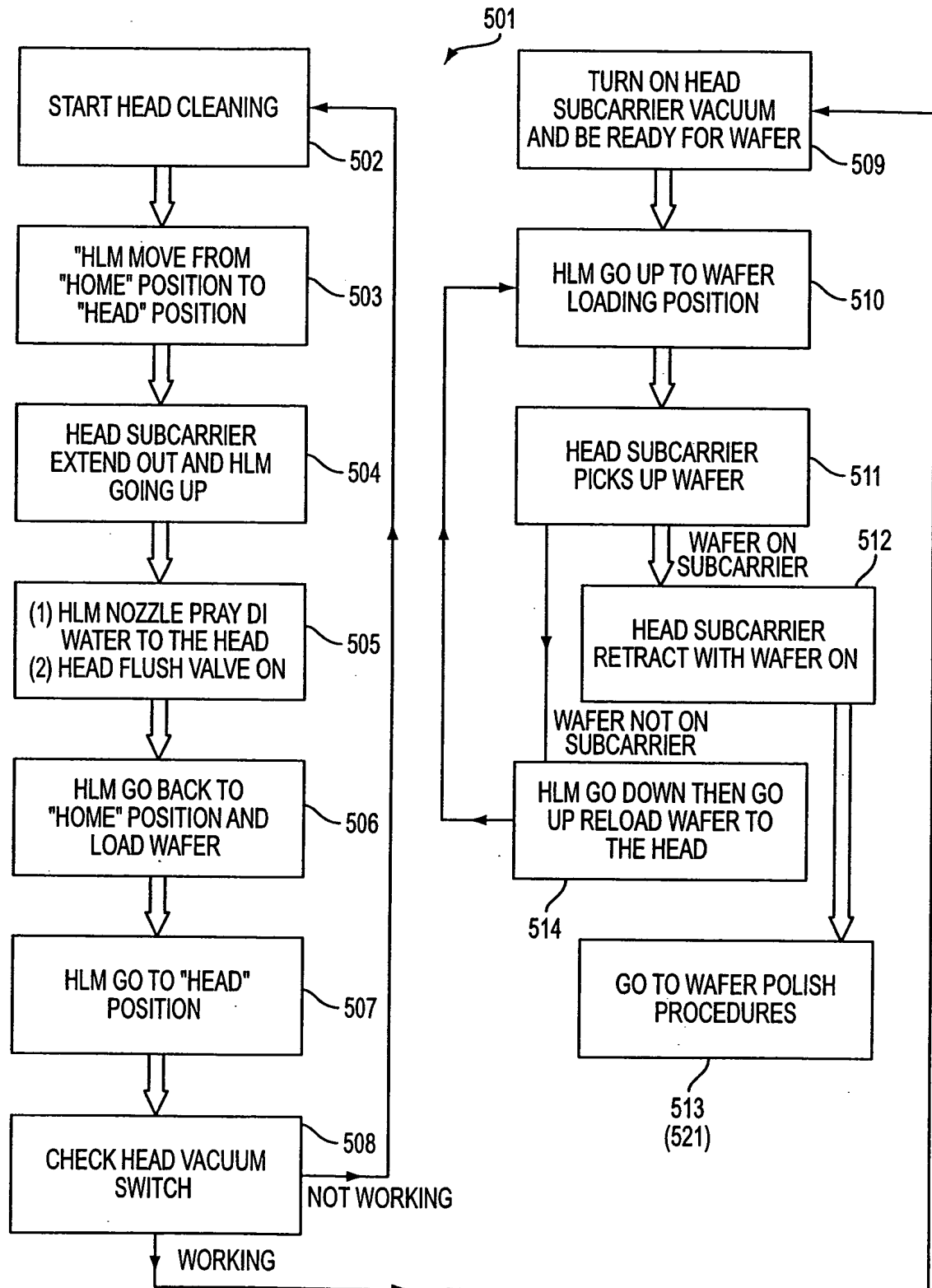
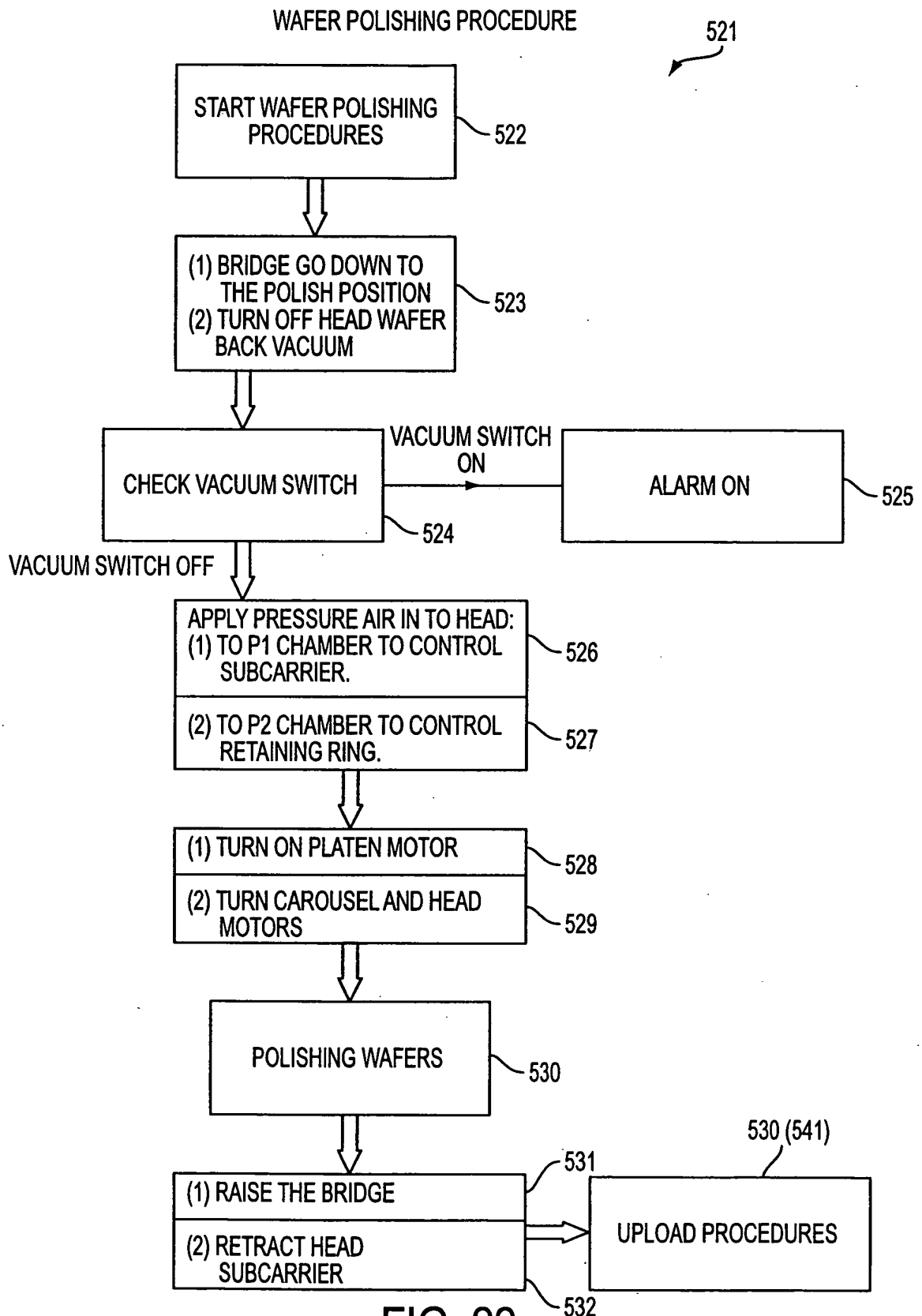


FIG. 21







# WAFER UNLOAD PROCEDURE

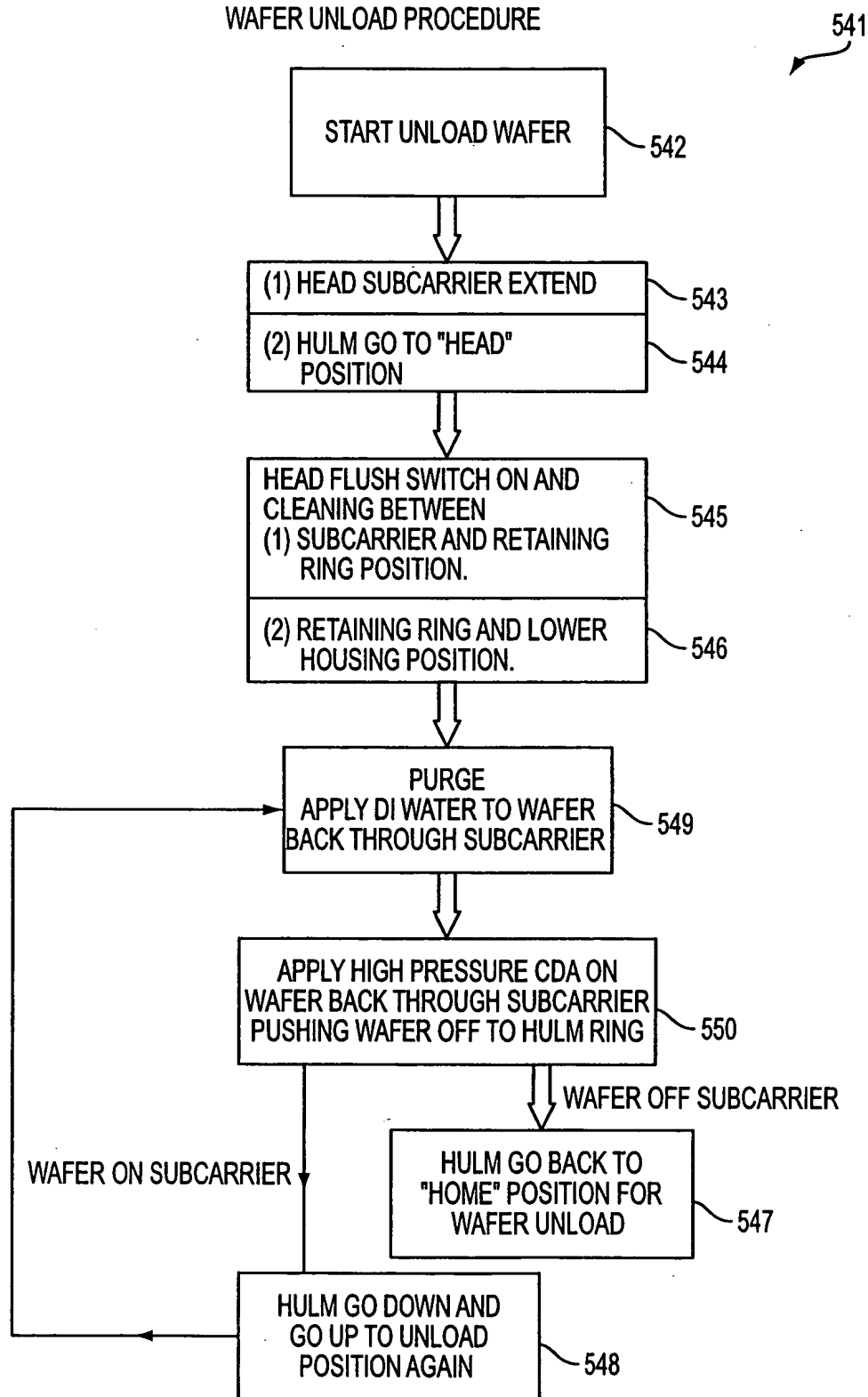


FIG. 23